

LOCTITE ABLESTIK ACP 3122

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PRODUCT DESCRIPTION

LOCTITE ABLESTIK ACP 3122 provides the following product characteristics:

Technology	Epoxy
Appearance	Golden Brown
Cure	Heat cure
Product Benefits	• Snap curable • Anisotropic electrically conductive • Low temperature cure • Optimized rheology • Electrically conductive in the z-axis only
Application	Assembly
Typical Assembly Applications	Copper circuitry, Gold plated terminators and Silver ink conductive traces

LOCTITE ABLESTIK ACP 3122 anisotropic, epoxy adhesive is designed for high throughput microelectronics assembly applications. This adhesive conducts only in one direction, making it suitable for small die and component attachment without the possibility of electrical shorting. LOCTITE ABLESTIK ACP 3122 requires pressure during cure to establish a reliable interconnect.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Rheometer, mPa·s (cP):

@ 15 s ⁻¹	22,000
@ 30 s ⁻¹	14,000

Shear Thinning Index (Rheometer) 6

Work Life @ 25°C, hours 24

Shelf Life @ -20°C, days 183

Flash Point - See SDS

TYPICAL CURING PERFORMANCE

Cure Schedule

5 seconds @ 150°C under optimum pressure, bondline temperature

LOCTITE ABLESTIK ACP 3122 requires pressure during cure to establish a reliable connection. Most dies up to 1 sq mm in size require a 1 to 3 Newtons to form a reliable interconnect. The optimum pressure is best determined for each new design. The recommended bonding condition for this adhesive is 5 seconds at a bondline temperature of 150°C. No post cure is required. Material properties will depend upon cure conditions used.

The above cure profile is a guideline recommendation. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Sample cured 10minutes @ 120°C in convection oven

Physical Properties :

Glass Transition Temperature, DMA, Tan Δ Max, °C 100

Storage Modulus, DMA, Ramp Rate 3°C/minute:

@ 25 °C	N/mm ²	2,400
	(psi)	(344,200)
@ 50 °C	N/mm ²	1,950
	(psi)	(282,200)
@ 100 °C	N/mm ²	220
	(psi)	(32,000)

TYPICAL PERFORMANCE OF CURED MATERIAL

Miscellaneous:

Die Shear Strength :

50 x 50 mil Si die to Copper/PET, Kg	2.2
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GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

DIRECTIONS FOR USE

1. Complete cleaning of the substrates should be performed to remove contamination such as oxide layers, dust, moisture, salt and oils which can cause poor adhesion or corrosion in a bonded part
2. Apply adhesive to all surfaces to be bonded and join together
3. In most applications only contact pressure is required

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage : -20 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\text{N} \times 0.225 = \text{lb}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{psi} \times 145 = \text{N/mm}^2$
 $\text{MPa} = \text{N/mm}^2$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

Reference 1**Disclaimer****Note:**

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